

SUN MICROELECTRONICS

***microSPARC-llep™***

*Introduction to JTAG  
Boundary Scan*

**White Paper**  
January 1997

# JTAG Boundary Scan Basics

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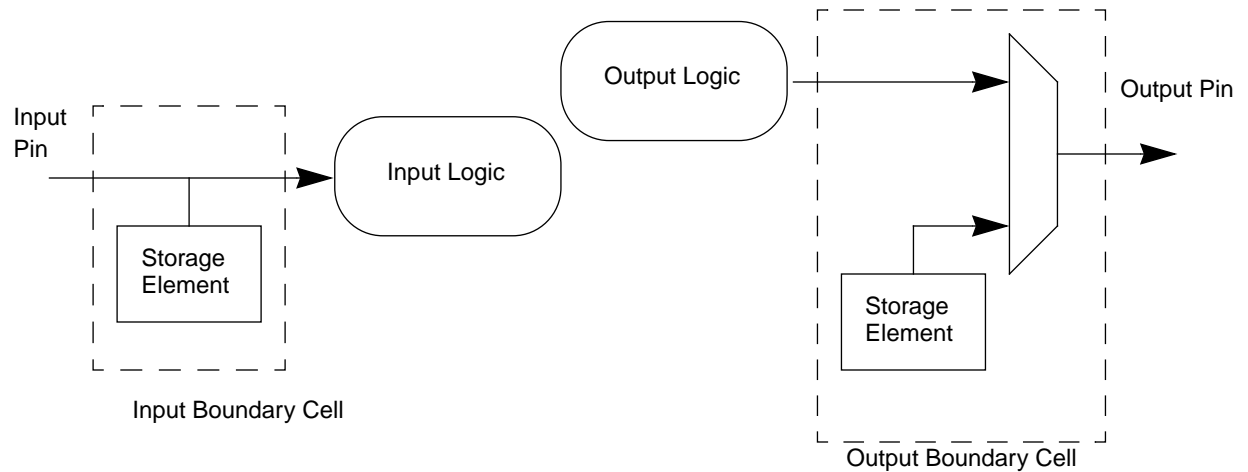
## **Introduction**

Historically, most Print Circuit Board (PCB) testing was done using bed-of-nail in-circuit test equipment. Recent advances with VLSI technology now enable microprocessors and Application Specific Integrated Circuits (ASICs) to be packaged into fine pitch, high count packages. These high density devices pose unique manufacturing challenges: such as, the accessibility of test points and the high cost of test equipment.

In 1985, a group of European companies formed Joint European Test Action Group (JETAG) to tackle these challenges. It called for incorporating hardware into standard components (controlled via software), eliminating the need for sophisticated in-circuit test equipment. By 1988, the concept gained momentum in North America and several companies formed the Joint Test Access Group (JTAG) consortium to formalize the idea. In 1990, the Institute of Electrical and Electronic Engineers (IEEE) refined the concept and created the 1149.1 standard, known as IEEE Standard Test Access Port and Boundary Scan Architecture.

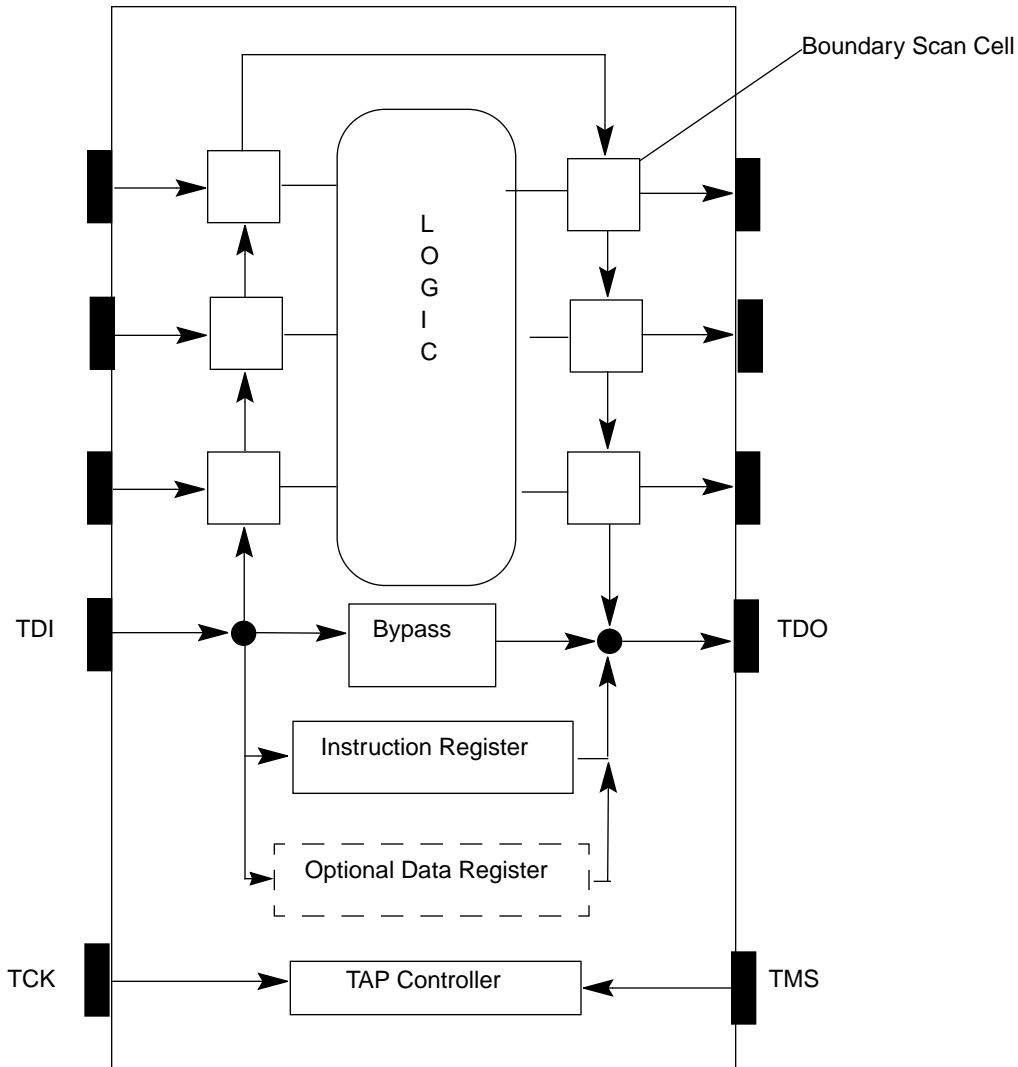
## What is Boundary Scan?

Boundary scan is a methodology allowing complete controllability and observability of the boundary pins of a JTAG compatible device via software control. This capability enables in-circuit testing without the need of bed-of-nail in-circuit test equipment.



**Figure 1. Input and Output Structure for a Boundary Scan Device (Simplified)**

Figure 1 illustrates possible structures for input and output pins of a JTAG-compliant device. During standard operations, boundary cells are inactive and allow data to be propagated through the device normally. During test modes, all input signals are captured for analysis and all output signals are preset to test down-string devices. The operation of these scan cells is controlled through the Test Access Port (TAP) Controller and the instruction register as shown in the following illustration, Figure 2.



**Figure 2. The Boundary Scan Device**

The TAP controller is a state machine (16 possible states) controlling operations associated with boundary scan cells. The basic operation is controlled through four pins: Test Clock (TCK), Test Mode Select (TMS), Test Data In (TDI), and Test Data Out (TDO).

The TCK and TMS pins direct signals between TAP controller states. The TDI and TDO pins receive the data input and output signals for the scan chain. Optionally, a fifth pin, TRST, can be implemented as an asynchronous reset signal to the TAP controller.

## Required Instructions

Working in conjunction with the TAP controller is an IR (Instruction Register) providing which type of test to perform. The 1149.1 Standard requires that all compliant devices must perform the following three instructions:

### 1. EXTEST Instruction

This instruction performs a PCB interconnect test. The EXTEST instruction places an IEEE 1149.1 compliant device into an external boundary test mode and selects the boundary scan register to be connected between TDI and TDO. During this instruction, the boundary scan cells associated with outputs are preloaded with test patterns to test downstream devices. The input boundary cells are set up to capture the input data for later analysis.

### 2. SAMPLE/PRELOAD Instruction

The SAMPLE/PRELOAD instruction allows an IEEE 1149.1 compliant device to remain in its functional mode and selects the boundary scan register to be connected between the TDI and TDO pins. During this instruction, the boundary scan register can be accessed via a data scan operation, to take a sample of the functional data entering and leaving the device. This instruction is also used to preload test data into the boundary-scan register prior to loading an EXTEST instruction.

### 3. BYPASS Instruction

A device's boundary scan chain can be skipped using the BYPASS instruction, allowing the data to pass through the bypass register. This allows efficient testing of a selected device without incurring the overhead of traversing through other devices. The BYPASS instruction allows an IEEE 1149.1 compliant device to remain in a functional mode and selects the bypass register to be connected between the TDI and TDO pins. The BYPASS instruction allows serial data to be transferred through a device from the TDI pin to the TDO pin without affecting the operation of the device.

### How Boundary Scan Testing Is Done

In a board design there usually can be many JTAG compliant devices. All these devices can be connected together to form a single scan chain as illustrated in Figure 3, "Single Boundary Scan Chain on a Board." Alternatively, multiple scan chains can be established so parallel checking of devices can be performed simultaneously.

Figure 3, "Single Boundary Scan Chain on a Board," illustrates the on onboard TAP controllers connected to an offboard TAP control device, such as a personal computer, through a TAP access connector. The offboard TAP control device can perform different tests during board manufacturing without the need of bed-of-nail equipment.

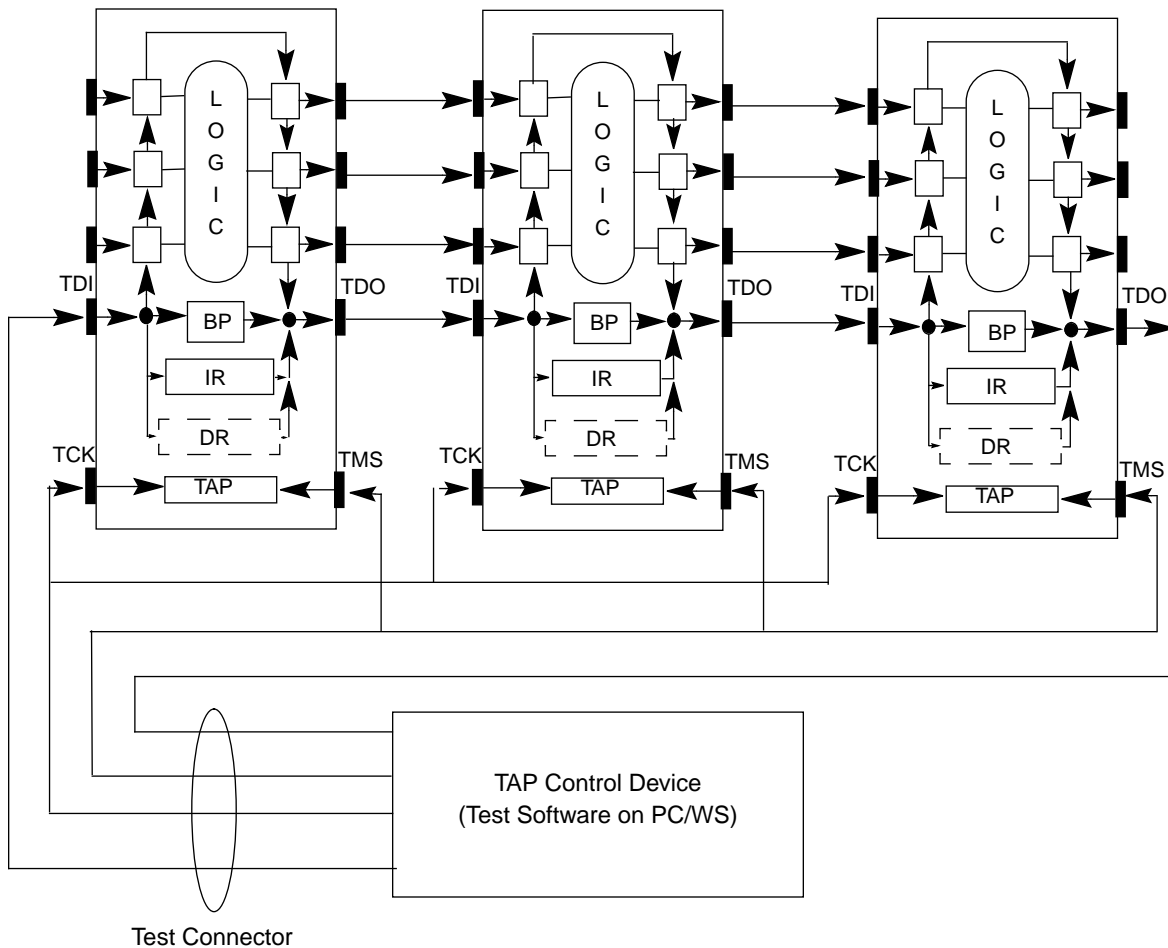


Figure 3. Single Boundary Scan Chain on a Board

## Simple Board Level Test Sequence

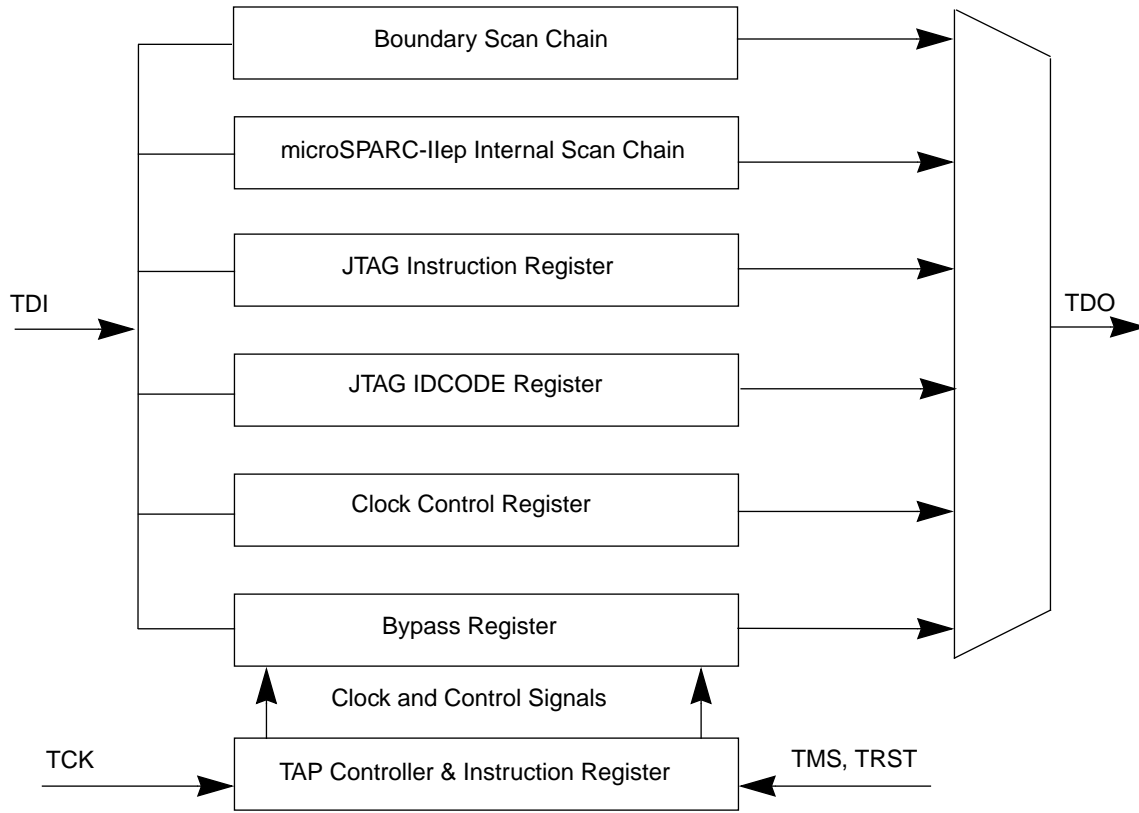
One of the first tests that should be performed for a PCB test is called the infra-structure test. This test is used to determine whether all the components are installed correctly. This test relies on the fact that the last two bits of the instruction register (IR) are always "01". By shifting out the IR of each device in the chain, it can be determined whether the device is properly installed. This is accomplished through sequencing the TAP controller for IR read.

After the infra-structure test is successful, the board level interconnect test can begin. This is accomplished through the EXTEST command. This test can be used to check out "opens" and "shorts" on the PCB. The test patterns are preloaded into the output pins of the driving devices. Then they are propagated to the receiving devices and captured in the input boundary scan cells. The result can then be shifted out through the TDO pin for analysis.

These patterns can be generated and analyzed automatically, via software programs. This feature is normally offered through tools like Automatic Test Pattern Generation (ATPG) or Boundary Scan Test Pattern Generation (BTPG).

## The microSPARC-IIep Boundary Scan Capability

The microSPARC-IIep chip implements the standard 1149.1 boundary scan architecture. It can be seamlessly integrated with other 1149.1 compliant devices to perform board level testing. In addition to the standard four-wire (TDI, TDO, TCK, and TMS) JTAG TAP access port, the microSPARC-IIep also implements the optional TRST signal line. This allows the on-chip TAP controller to be reset asynchronously. See Figure 4, "microSPARC-IIep Scan Chain Organization," for an illustrated description of how the scan chain is organized in the IIep chip.



**Figure 4. microSPARC-IIep Scan Chain Organization**

In addition to the three instructions required by the 1149.1 Standard (see "Required Instructions" on page 4), the microSPARC-IIep also implements other instructions, see Table 1, "microSPARC-IIep JTAG Commands." These instructions allow different tests to be performed when the microSPARC-IIep is used as a component in a board or system environment. See the microSPARC-IIep User's Manual for a more detailed description.



**Table 1. microSPARC-IIep JTAG Commands**

<b>Instruction</b>	<b>IR Value</b>	<b>Registers</b>	<b>Function</b>
EXTEST	000000	Boundary	PCB Interconnect test
SAMPLE	000001	Boundary	Sample and data preload
BYPASS	111111	Bypass	Bypass mode
SEL_INT_SCAN	010000	Internal Scan Reg.	Scan IIep internal register
SEL_DBG_SCAN	011111	Internal Scan Reg.	Scan IIep internal register
IDCODE	100000	JTAG ID Reg.	Scan the ID register
SEL_CCR	011110	Clock Control Reg.	Set up clock control
CLK_RST	100000	Bypass	Reset Clock Control

## **Conclusion**

Board level testing has become more complex with the increasing use of fine pitch, high pin count devices. However with the use of boundary scan the implementation of board level testing is done more efficiently and at lower cost. The microSPARC-IIep chip fully supports use of the JTAG boundary scan; enabling it to seamlessly integrate with other IEEE 1149.1 compliant devices on a PCB, as well as permitting microSPARC-IIep chip to be board level tested without the PCB expense of complex in-circuit test equipment.



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